RoHS

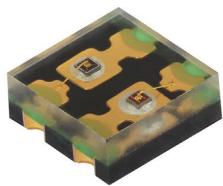
HALOGEN **FREE**

GREEN



Vishay Semiconductors

Dual Color Emitting Diodes, 660 nm and 940 nm



VSMD66694 is a dual color emitting device with 660 nm and

940 nm peak wavelength. The emitters are based on the <u>SurfLightTM</u> technology, providing high radiant power.

FEATURES

- Package type: surface-mount
- Package form: square PCB
- Dimensions (L x W x H in mm): 2 x 2 x 0.87
- Peak wavelength: $\lambda_p = 660 \text{ nm}$ and 940 nm
- High reliability
- · High radiant power
- Angle of half intensity: $\varphi = \pm 60^{\circ}$
- Floor life: 168 h, MSL 3, according to J-STD-020
- · Lead (Pb)-free reflow soldering
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



- Wearables
- · Health monitoring
- · Pulse oximetry

PRODUCT SUMMARY					
COMPONENT	COLOR	I _e (mW/sr)	φ (°)	$λ_{\mathbf{p}}$ (nm)	t _r (ns)
VSMD66694	Red	2.3	± 60	660	10
VSIVID00094	IR	1.5		940	10

Note

DESCRIPTION

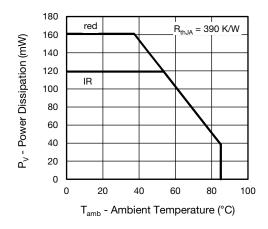
Test conditions see table "Basic Characteristics"

ORDERING INFORMATION				
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM	
VSMD66694	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	square PCB	

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)					
PARAMETER	TEST CONDITION	SYMBOL	COLOR	VALUE	UNIT
Reverse voltage		V _R		5	V
Forward ourrent			Red	70	mA
Forward current		I _F	IR	70	
Peak forward current	$t_p/T = 0.1, t_p = 100 \mu s$,	Red	140	mA
		I _{FM}	IR	140	
Course forward course	t _p = 100 μs		Red	1	Α
Surge forward current		I _{FSM}	IR	1	
Power dissipation		Б	Red	161	mW
		P _V	IR	119	
Junction temperature		Tj		100	°C
Operating temperature range		T _{amb}		-25 to +85	°C
Storage temperature range		T _{stg}		-25 to +85	°C
Soldering temperature	According fig. 10, J-STD-020	T _{sd}		260	°C
Thermal resistance junction to ambient	J-STD-051	R _{thJA}		390	K/W







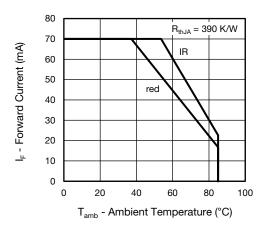
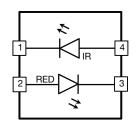


Fig. 2 - Forward Current Limit vs. Ambient Temperature

PARAMETER	TEST CONDITION	SYMBOL	COLOR	MIN.	TYP.	MAX.	UNIT
Forward voltage	$I_F = 20 \text{ mA}, t_p = 20 \text{ ms}$	V _F	Red	-	2.0	2.3	V
			IR	-	1.4	1.7	
	J 00 A	TK _{VF}	Red	-	-2.3	-	mV/K
Temperature coefficient	$I_F = 20 \text{ mA}$		IR	-	-2.3	-	
Reverse current		I _R	not o	designed for	reverse oper	ation	μΑ
lunction conscitance	$V_R = 0 V$, $f = 1 MHz$,	_	Red	-	7	-	pF
Junction capacitance	$E = 0 \text{ mW/cm}^2$	CJ	IR	-	5	-	
Dealth of Salarasii	J 00 A		Red	1.9	2.3	-	mW/sr
Radiant intensity	$I_F = 20 \text{ mA}$	l _e	IR	0.8	1.5	-	
Padical access	J 00 A	фе	Red	-	9.5	-	mW
Radiant power	$I_F = 20 \text{ mA}$		IR	-	8.5	-	
Angle of half intensity	I _F = 20 mA	φ		-	± 60	-	0
Park a desette	I _F = 20 mA	2	Red	650	660	670	nm
Peak wavelength		λ_{p}	IR	920	940	960	nm
Spectral bandwidth	I _F = 20 mA	Δλ	Red	-	20	-	nm
			IR	-	40	-	
Temperature coefficient of $\boldsymbol{\lambda}_p$	I _F = 20 mA	TK_{\lambdap}	Red	-	0.2	-	nm/K
			IR	-	0.3	-	
Rise time	I _F = 20 mA	t _r	Red	-	10	-	ns
			IR	-	10	-	
Fall time	I _F = 20 mA	t _f	Red	-	10	-	ns
			IR	-	10	-	

CIRCUIT BLOCK DIAGRAM



1	IR LED	IR cathode
2	RED LED	RED anode
3	RED LED	RED cathode
4	IR LED	IR anode

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

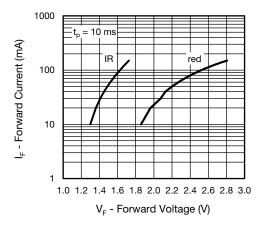


Fig. 3 - Forward Current vs. Forward Voltage

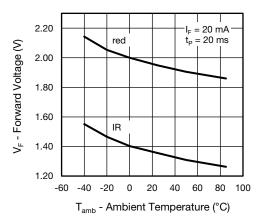


Fig. 4 - Forward Voltage vs. Ambient Temperature

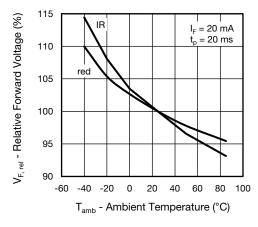


Fig. 5 - Relative Forward Voltage vs. Ambient Temperature

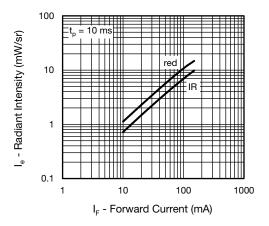


Fig. 6 - Radiant Intensity vs. Forward Current

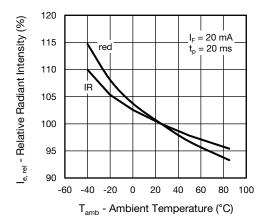


Fig. 7 - Relative Radiant Intensity vs. Ambient Temperature

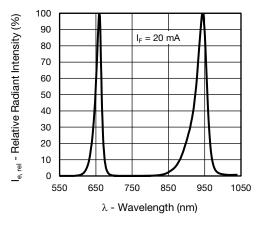


Fig. 8 - Relative Radiant Intensity vs. Wavelength



Fig. 9 - Relative Radiant Intensity vs. Angular Displacement

REFLOW SOLDER PROFILE

948013-5

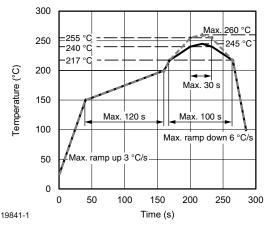


Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

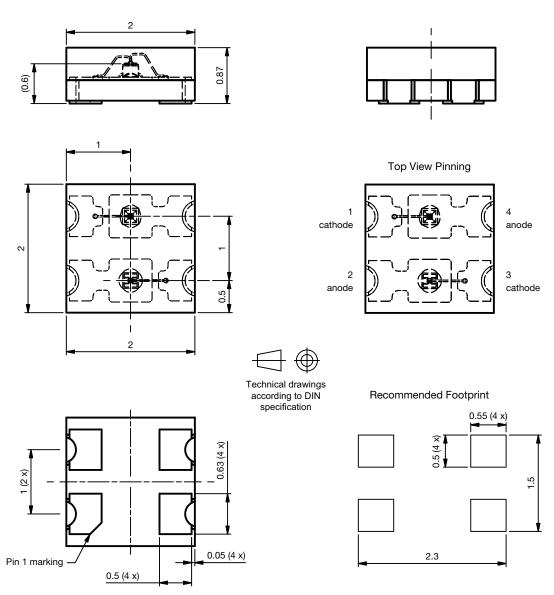
Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 $^{\circ}$ C (+ 5 $^{\circ}$ C), RH < 5 $^{\circ}$ M.



PACKAGE DIMENSIONS in millimeters



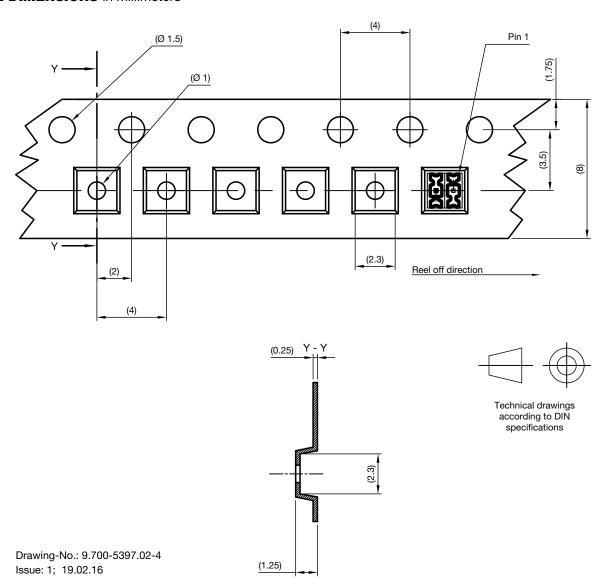
Drawing No.: 6.550-5347.01-4

Issue: 1; 19.02.16

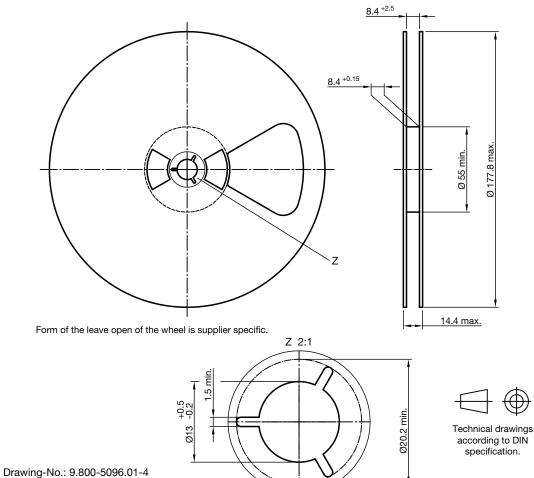
Not indicated tolerances \pm 0.1



TAPE DIMENSIONS in millimeters



REEL DIMENSIONS in millimeters



Issue: 5; 20.12.2016



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Vishay

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